

**PATENT APPLICATION**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q76625

YAMAMOTO, Shouji

Appln. No.: Divisional of USAN 09/793,108

Confirmation No.: 2523 (parent)

Group Art Unit: 1711 (parent)

Filed: July 21, 2003

Examiner: Susan W. Berman (parent)

For: UV-CURABLE PRESSURE-SENSITIVE ADHESIVE COMPOSITION AND ITS  
PRESSURE-SENSITIVE ADHESIVE SHEET

**PRELIMINARY AMENDMENT**

**MAIL STOP NON-FEE AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Prior to examination, please amend the above-identified application as follows:

**IN THE CLAIMS:**

**Please cancel claims 1-7 without prejudice or disclaimer.**

**Please add the following new claims:**

8. (New) A method for processing a semiconductor wafer comprising the steps of:  
adhering a pressure-sensitive adhesive sheet to a semiconductor wafer, the pressure-sensitive adhesive sheet comprising a photo-transmitting base film, and a layer comprising an ultraviolet-curable pressure-sensitive adhesive composition comprising a photoinitiator having a molar absorptivity at 365 nm of at least  $1,000 \text{ mol}^{-1} \cdot \text{cm}^{-1}$  and a maximum absorption wavelength of at least 420 nm;

exposing the pressure-sensitive adhesive sheet to an ultraviolet ray; and  
peeling the pressure-sensitive adhesive sheet from the semiconductor wafer.